

#### **Product Overview**

The Qorvo QPD1029L is a 1500 W (P<sub>3dB</sub>) discrete GaN on SiC HEMT which operates from 1.2 to 1.4 GHz. Input prematch within the package results in ease of external board match and saves board space. The device is in an industry standard air cavity package and is ideally suited for radar The device can support both CW and pulsed operations.

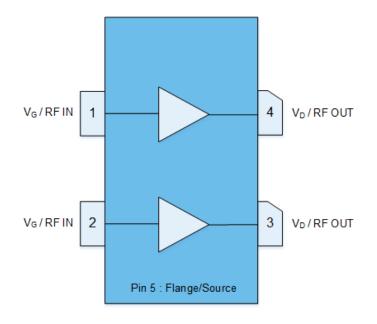
#### RoHS compliant

Evaluation boards are available upon request.



4-lead NI-1230 Package (Eared)

### **Functional Block Diagram**



### **Key Features**

Frequency: 1.2 to 1.4 GHz
Output Power (P<sub>3dB</sub>)<sup>1</sup>: 1500 W

Linear Gain<sup>1</sup>: 21.3 dB
Typical PAE<sub>3dB</sub><sup>1</sup>: 75%
Operating Voltage: 65 V
CW and Pulse capable

Note 1: @ 1.3 GHz Load Pull

### **Applications**

• L-Band radar-amplifier application

### **Ordering info**

Part No.	Description	
QPD1029L	1.2 – 1.4 GHz Transistor (18 pcs in tray)	
QPD1029LEVB4	1.2 – 1.4 GHz Evaluation Board	



### **Absolute Maximum Ratings** 1, 2, 3

Parameter	Rating	Units
Breakdown Voltage,BV <sub>DG</sub>	225	V
Gate Voltage Range, V <sub>G</sub>	-7 to +2	V
Drain Current, I <sub>DMAX</sub>	142	Α
Gate Current Range, I <sub>G</sub>	See pg. 12	mA
Power Dissipation, Pulsed, PDISS <sup>2</sup>	1728	W
RF Input Power, Pulsed, P <sub>IN</sub> <sup>3</sup>	46.2	dBm
Mounting Temperature (30 Seconds)	320	°C
Storage Temperature	−65 to +150	°C

#### Notes:

- Operation of this device outside the parameter ranges given above may cause permanent damage
- 2. Pulsed, 300us PW, 10% DC, Package base at 85 °C
- 3. Pulsed, 300us PW, 10% DC, T = 25 °C

#### **Recommended Operating Conditions 1, 2, 3, 4**

Parameter	Min	Тур	Max	Units
Operating Temp. Range	-40	+25	+85	°C
Drain Voltage Range, V <sub>D</sub>	_	+65	+70	V
Drain Bias Current, I <sub>DQ</sub>		1.5		Α
Drain Current, I <sub>D</sub> <sup>4</sup>	_	45	_	Α
Gate Voltage, V <sub>G</sub> <sup>3</sup>	_	-2.8	_	V
Power Dissipation (P <sub>D</sub> ) <sup>2,4</sup>	_	_	865	W
Power Dissipation (P <sub>D</sub> ), CW <sup>2</sup>	_	_	467	W

#### Notes:

- Electrical performance is measured under conditions noted in the electrical specifications table. Specifications are not guaranteed over all recommended operating conditions
- 2. Package base at 85 °C
- 3. To be adjusted to desired IDQ
- 4. Pulsed, 300us PW, 10% DC

#### Measured Load Pull Performance - 65V Power Tuned 1,2

Parameter		Typical Value	s	Units
Frequency, F	1.2	1.3	1.4	GHz
Output Power at 3dB compression, P <sub>3dB</sub>	60.1	60.1	59.9	dBm
Drain Efficiency at 3dB compression, DEff <sub>3dB</sub>	63.7	62.5	64.4	%
Gain at 3dB compression, G <sub>3dB</sub>	17.3	16.5	16.9	dB

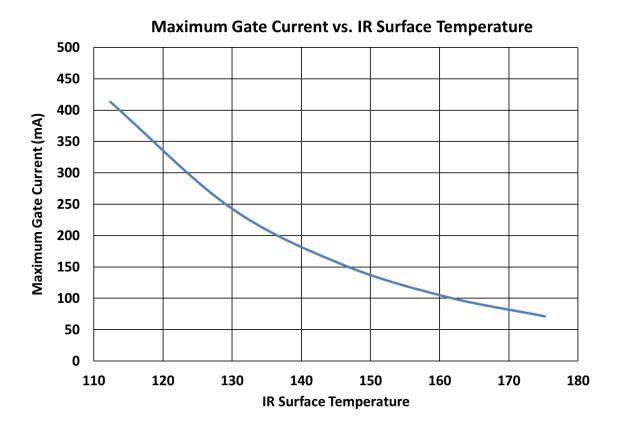
#### Notes:

- 1. Test conditions unless otherwise noted: T<sub>A</sub> = 25 °C, V<sub>D</sub> = 65 V, I<sub>DQ</sub> = 750 mA (half device)
- 2. Pulsed, 100 us Pulse Width, 10% Duty Cycle.

### Measured Load Pull Performance - 65V Efficiency Tuned 1,2

Parameter		Typical Value	s	Units
Frequency, F	1.2	1.3	1.4	GHz
Output Power at 3dB compression, P <sub>3dB</sub>	58.5	58.5	58.5	dBm
Drain Efficiency at 3dB compression, D Eff <sub>3dB</sub>	78.7	76.4	76.4	%
Gain at 3dB compression, G <sub>3dB</sub>	18.8	18.5	18.2	dB

- 1. Test conditions unless otherwise noted: T<sub>A</sub> = 25 °C, V<sub>D</sub> = 65 V, I<sub>DQ</sub> = 750 mA (half device)
- 2. Pulsed, 100 us Pulse Width, 10% Duty Cycle.



#### RF Characterization - 1.2 - 1.4 GHz EVB4 Performance at 1.3 GHz <sup>1</sup>

Parameter	Min	Тур	Max	Units
Linear Gain, G <sub>LIN</sub>	_	19.8	_	dB
Output Power at 3dB compression point, P3dB	_	1350	_	W
Drain Efficiency at 3dB compression point, DEFF3dB	_	65	_	%
Gain at 3dB compression point, G3dB	_	16.5	_	dB
Gate Leakage $V_D = +10 \text{ V}, V_G = -3.3 \text{ V}$	- 40	_	_	mA

#### Notes:

### RF Characterization – Mismatch Ruggedness at 1.2, 1.3, 1.4 GHz <sup>1, 2, 3</sup>

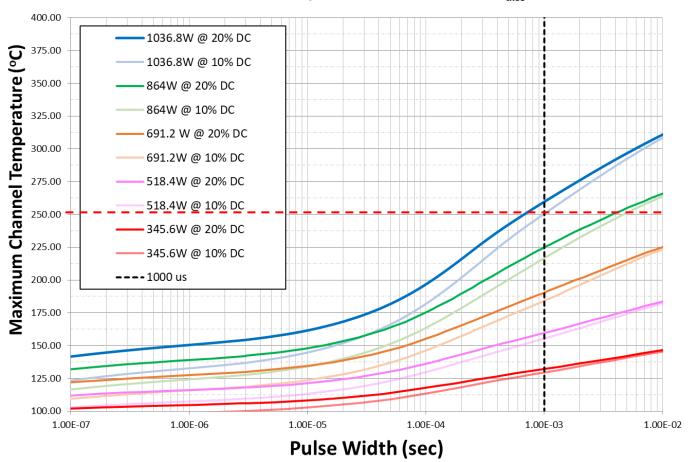
Symbol	Parameter	dB Compression	Typical
VSWR	Impedance Mismatch Ruggedness	3	10:1

- Test conditions unless otherwise noted: T<sub>A</sub> = 25 °C, V<sub>D</sub> = 65 V, I<sub>DQ</sub> = 1.5 A (combined)
- Input drive power is determined at pulsed 3dB compression under matched condition at EVB output connector
- 3. Pulse: 100us, 10% Duty cycle

<sup>1.</sup>  $V_D = 65 \text{ V}$ ,  $I_{DQ} = 1.5 \text{ A}$  (combined), Temp = +25 °C, Pulse Width = 100 us, Duty Cycle = 10%



# Peak IR Surface Temperature vs. Pulse Width Base temperature fixed at 85 °C, P<sub>diss</sub> Varies



Parameter	Conditions	Values	Units
Thermal Resistance, IR¹ (θ <sub>JC</sub> )	85 °C Case backside Temperature	0.10	°C/W
Peak IR Surface Temperature <sup>1</sup> (T <sub>ch</sub> )	Pdiss = 518 W, Pulse: 300 us PW, 10% DC	139	°C

#### Notes:

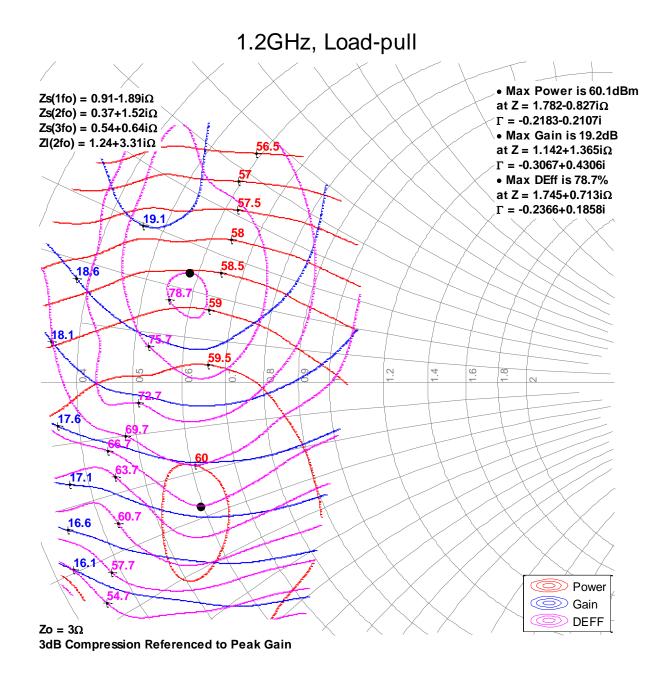
1. Refer to the following document <u>GaN Device Channel Temperature</u>, <u>Thermal Resistance</u>, <u>and Reliability Estimates</u>

# Thermal and Reliability Information – Pulsed <sup>1</sup>



### Measured Load-Pull Smith Charts at 65V 1, 2, 3

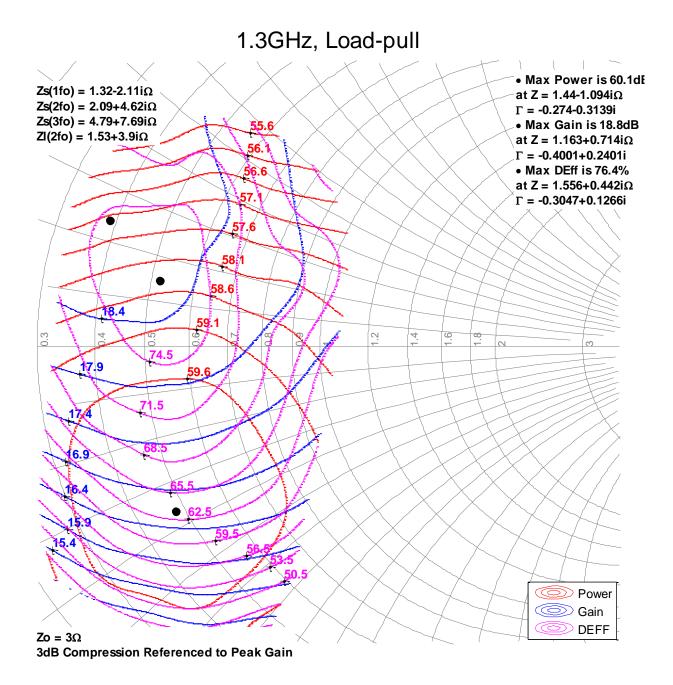
- 1. Test Conditions: V<sub>D</sub> = 65 V, I<sub>DQ</sub> = 750 mA, 100 us Pulse Width, 10% Duty Cycle, Temp = 25°C.
- 2. The performance shown below is for only half of the device out of the two independent amplification paths.
- 3. See "Pin Configuration and Description" for load pull reference planes where the performance was measured.





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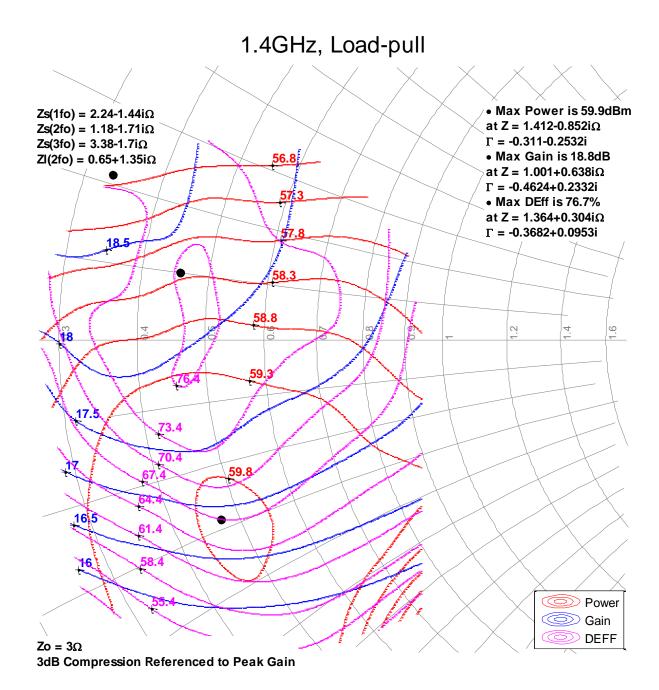
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### Typical Measured Performance - Load-Pull Drive-up at 65V 1, 2, 3

#### Notes:

18.7

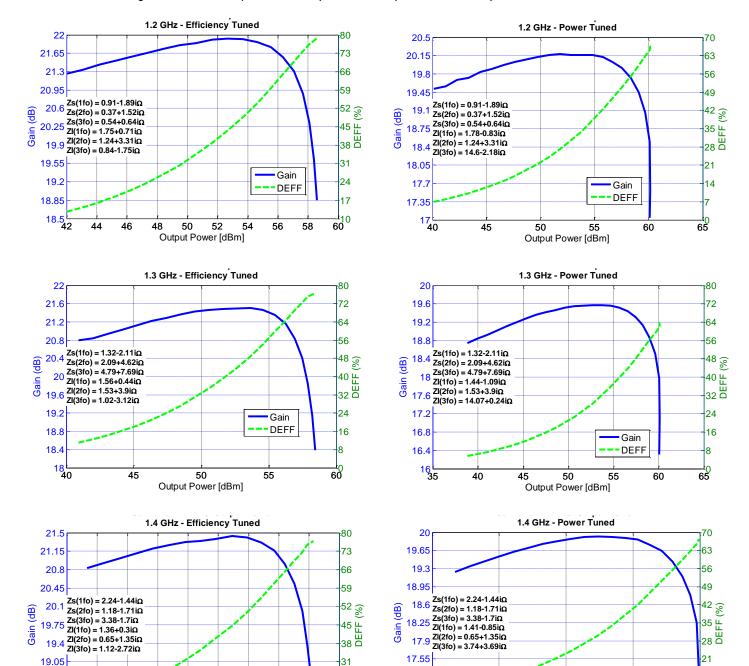
18.35

1<mark>8</mark>∟ 42

44

46

- 1. Test Conditions: V<sub>D</sub> = 65 V, I<sub>DQ</sub> = 750 mA, 100 us Pulse Width, 10% Duty Cycle, Temp = 25°C.
- 2. The performance shown below is for only half of the device out of the two independent amplification paths.
- 3. See "Pin Configuration and Description" for load pull reference planes where the performance was measured.



50

Output Power [dBm]

52

Gain

DEFF

58

56

24

17

<del>\_</del><sup>t</sup>10</del>

17.2

16.85

16.5 40 14

Gain

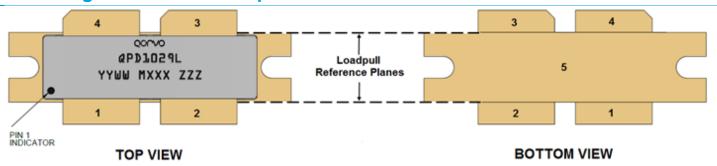
--DEFF

55

Output Power [dBm]



# Pin Configuration and Description <sup>1</sup>



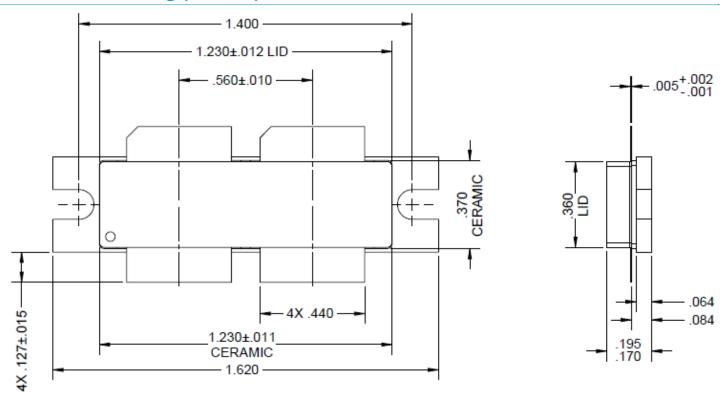
#### Note:

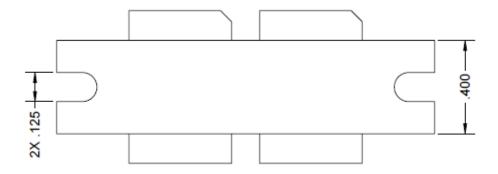
1. The QPD1029L will be marked with the "QPD1029L" designator and a lot code marked below the part designator. The "YY" represents the last two digits of the calendar year the part was manufactured, the "WW" is the work week of the assembly lot start, the "MXXX" is the production lot number, and the "ZZZ" is an auto-generated serial number.

Pin	Symbol	Description
1, 2	RF IN / V <sub>G</sub>	Gate
3, 4	RF OUT / V <sub>D</sub> Drain	
5	Source	Source / Ground / Backside of part



# Mechanical Drawing (NI-1230)<sup>1-7</sup>

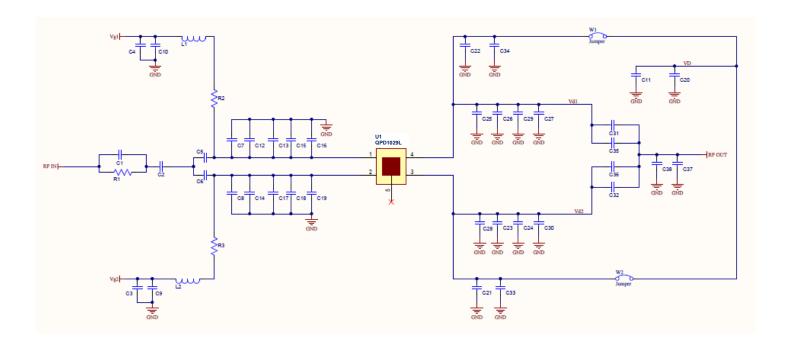




- 1. All dimensions are in inches.
- 2. Dimension tolerance is  $\pm$  0.005 inches, unless noted otherwise.
- 3. Package base: Ceramic/Metal, Package lid: Ceramic
- 4. Package Metal base and leads are gold plated
- 5. Parts are epoxy sealed.
- 6. Parts meet industry NI1230 footprint
- 7. Body dimensions do not include runout which can be up to 0.020 inches per side.



# 1.2 – 1.4 GHz Application Circuit - Schematic

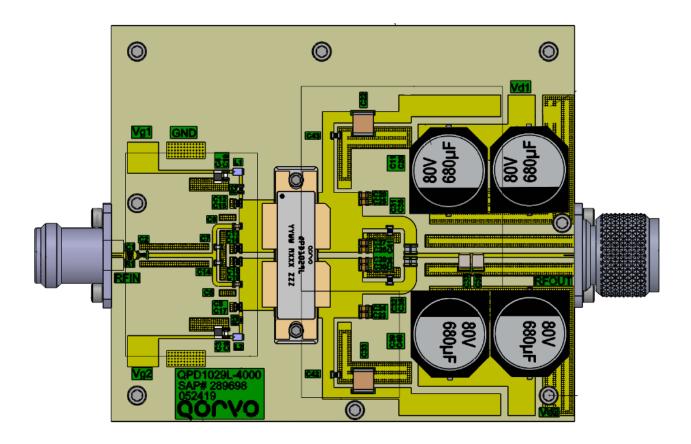


Bias-up Procedure	Bias-down Procedure
1. Set $V_G$ to -5 $V$ .	1. Turn off RF signal.
2. Set I <sub>D</sub> current limit to 2 A.	2. Turn off V <sub>D</sub>
3. Apply 65 V V <sub>D</sub> .	3. Wait 2 seconds to allow drain capacitor to discharge.
4. Slowly adjust V <sub>G</sub> until I <sub>D</sub> is set to 1.5 A.	4. Turn off V <sub>G</sub>
5. Apply RF.	



# 1.2 - 1.4 GHz Application Circuit EVB4 - Layout 1, 2, 3

- 1. PCB material is RO4350B 0.020" thick, 2 oz. copper each side.
- 2. The two gates could be tied together or (optionally) adjusted independently.
- 3. EVB is rated for pulsed operation only





# 1.2 – 1.4 GHz Application Circuit – Bill of Material EVB4

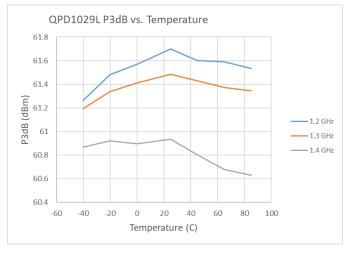
Ref Des	Qty	Description	Mfg Name	Mfg Part #
		1500W, 65V, Pre-matched, 1.2-1.4GHz,	_	_
U1	1	Fla	Qorvo	QPD1029L
			American Technical	
C7,C14	2	CAP, 3.0PF, +/-0.1pF, 250V, HI-Q, 0603	Ceramics	600S3R0BW250XT
			American Technical	
C1,C2	2	CAP, 24pF, 1%, 250V, COG, 0603	Ceramics	600S240FT250XT
			American Technical	
C31,C32,C35,C36	4	CAP, 2.2pF, 0.1pF, 250V, C0G, 0805	Ceramics	600F2R2BT250XT
			American Technical	
C23,C25,C26,C30	4	CAP, 3.3pF, 0.1pF, 250V, C0G, 0805	Ceramics	600F3R3BT250XT
			American Technical	
C24,C27,C28,C29,C34,C41	6	CAP, 3.9pF, 0.1pF, 250V, C0G, 0805	Ceramics	600F3R9BT250XT
			American Technical	
C9,C10	2	CAP, 27pF, 5%, 250V, NP0, 0603	Ceramics	600S270JT250XT
CF	_	CAR 02: F F0/ 2F0// III O COC 0502	American Technical	COOCOCOLTAGOVT
C5,C6	2	CAP, 82pF, 5%, 250V, HI-Q, C0G, 0603	Ceramics	600S820JT250XT
CO C12 C12 C15 C16 C17 C10 C10	8	CAR 2.75F 0.15F 2F0V 0602	American Technical	COCCUPANTALOVE
C8,C12,C13,C15,C16,C17,C18,C19	0	CAP, 2.7pF, 0.1pF, 250V, 0603	Ceramics	600S2R7BT250XT
			MURATA ELECTRONICS	
C3,C4	2	CAP, 4.7uF, 10%, 50V, X7R, 1206	SINGAPORE PTE LT	GRM31CR71H475KA12L
		CAI, 4.7 di, 1070, 50 V, X7 K, 1200	TDK SINGAPORE	GRIVISTER/THATSKATZE
C22,C33	2	CAP, 10uF, 20%, 100V, X7S, 2220	(PTE) LTD	C5750X7S2A106M230KB
022,033		Crit , 1001 , 2070, 100 V , 77 0 , 2220	American Technical	CS7 SOXT SEX LEGGINES ON B
C42,C43	2	CAP, 47pF, 5%, 250V, HI-Q, 0805	Ceramics	600F470JT250XT
		,p.,,	VISHAY AMERCIAS	
C11,C20,C39,C40	2	CAP, 680uF, ±20%, 80V, Alum Cap, SMD	INC	MAL215099708E3
		CAP, 1.8pF, 0.1 pF, 500V, COG, 1111,	American Technical	
C37,C38	2	SMD	Ceramics	800B1R8BT500XT
·			KOA Speer	
R2,R3	2	RES, 10 OHM, 1%, 0.1W, 0603	Electronics, Inc.	RK73H1JTTD10R0F
R1	1	RES, 100 OHM, 1%, 0.1W, 0603	Kamaya, Inc	RMC1/16K1000FTP
	_	, 200 0, 170, 0.211, 0000	VISHAY AMERCIAS	
R1	1	RES, 100 OHM, ±5%, 1/10W, 0603	INC	CRCW0603100RJNTA
<del></del>	_	,, .,, .,,,	Panasonic Industrial	
R1	1	RES, 100 OHM, 1%, 1/10W, 0603	Devices Sales	ERJ-3EKF1000V
L1,L2	2	Ind0805 WW 110nH ROHS	Coilcraft, Inc.	0805CS-111XGRC
L1,L2	2	IND, 110nH, 5%, W/W, 0805	Coilcraft, Inc.	0805CS-111XJBC
,		CONN, SERIES N, STRIPLINE LAUNCHER,	HUBER+SUHNER,	
RFOUT	1	MALE	Inc.	22642834
		CONN, COAXIAL, 11 GHz, N-FLANGE,	HUBER+SUHNER,	
RFIN	1	FEMALE	Inc.	23 N-50-0-33/133 NE

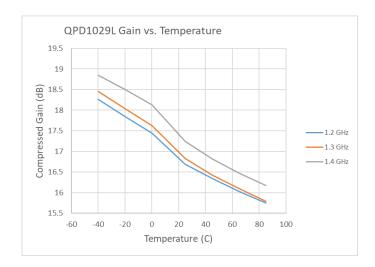


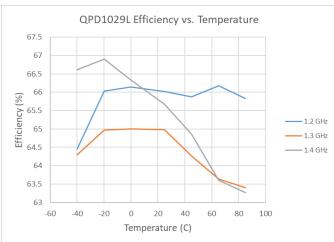
### Power Driveup Performance over Temperatures of 1.2 – 1.4 GHz EVB1 <sup>1</sup>

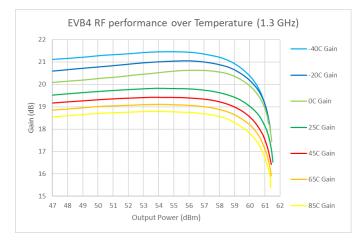
#### Notes:

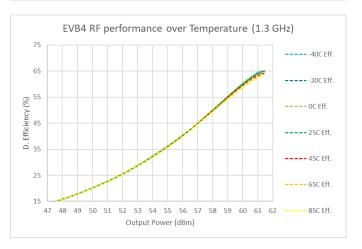
1. Test Conditions:  $V_D = 65 \text{ V}$ ,  $I_{DQ} = 1.5 \text{ A}$ , 100 us Pulse Width, 10% Duty Cycle.





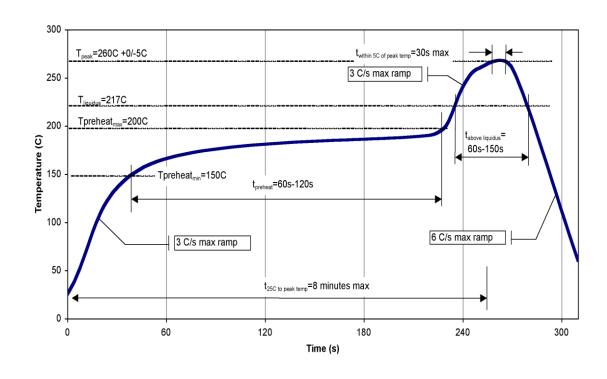








# **Recommended Solder Temperature Profile**





### **Handling Precautions**

Parameter	Rating	Standard
ESD-Human Body Model (HBM)	Class 1B	JEDEC JS-001
ESD - Charged Device Model (CDM)	Class C3	JEDEC JS-002
MSL-Moisture Sensitivity Level	MSL3	JESD J-STD-020 (260°C Convection reflow)



Caution! ESD-Sensitive Device

### **Solderability**

Compatible with both lead-free (260°C max. reflow temp.) and tin/lead (245°C max. reflow temp.) soldering processes.

Solder profiles available upon request.

The use of no-clean solder to avoid washing after soldering is recommended.

Contact plating: NiAu. Minimum Au thickness is 100micro-inches

### **RoHS Compliance**

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Halogen Free (Chlorine, Bromine)
- · Antimony Free
- TBBP-A (C<sub>15</sub>H<sub>12</sub>Br<sub>4</sub>O<sub>2</sub>) Free
- PFOS Free
- SVHC Free

#### **Contact Information**

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about Qorvo:

Web: <u>www.qorvo.com</u> Tel: +1.844.890.8163

Email: info-sales@qorvo.com

For technical questions and application information: Email: info-products@gorvo.com

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MAAM-009633-001SMB MASW-000936-001SMB 107712-HMC369LP3 107780-HMC322ALP4 SP000416870 EV1HMC470ALP3
EV1HMC520ALC4 EV1HMC244AG16 MAX2614EVKIT# 124694-HMC742ALP5 SC20ASATEA-8GB-STD MAX2837EVKIT+
MAX2612EVKIT# MAX2692EVKIT# EV1HMC629ALP4E SKY12343-364LF-EVB 108703-HMC452QS16G EV1HMC863ALC4
EV1HMC427ALP3E 119197-HMC658LP2 EV1HMC647ALP6 ADL5725-EVALZ MAX2371EVKIT# 106815-HMC441LM1
EV1HMC1018ALP4 UXN14M9PE MAX2016EVKIT EV1HMC939ALP4 MAX2410EVKIT MAX2204EVKIT+ EV1HMC8073LP3D
SIMSA868-DKL SIMSA868C-DKL SKY65806-636EK1 SKY68020-11EK1 SKY67159-396EK1 SKY66181-11-EK1